

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended) An integrated circuit device assembled in a package having a plurality of die including a first device and ~~at least one~~ an additional device, the IC comprising:

~~a substrate~~ substrate;

a first device die, having bonding pads including ground connections, the first device die attached to the ~~substrate and~~ substrate;

an additional device die having bonding pads including ground connections, the additional device die disposed on top of the first device ~~die~~ die, the additional device die attached to the first device die, wherein the ground connections of the first device die are connected to the ground connections of the additional device die; and

a conductive adhesive disposed between the first device die and the second device die, wherein the ground connections of the first device die are connected to the ground connections of the additional device die with the conductive adhesive.

2. (canceled)

3. (currently amended) The IC of ~~claim 2~~ claim 1 wherein the ground connections may be at voltages other than zero.

4. (currently amended) The IC of ~~claim 2 further comprising,~~ claim 1 further comprising an insulating material placed in between the first device die and the additional device die, the insulating material having openings allowing for the connecting of ground connections there-through between the first device die and the ~~second device~~ additional device die.

5. (currently amended) The IC of claim 4 ~~wherein,~~ wherein the conductive adhesive is flowed through the openings in the insulating material connecting the ground connections between the first device die and the ~~second device~~ additional device die.

6. (currently amended) The IC of ~~claim 2,~~ claim 1 further comprising: a package ground connection, wherein the package ground connection is connected to the ground connections of the first device die and the additional device die at a plurality of predetermined locations.

7. (currently amended) The IC of claim 1 ~~wherein,~~ wherein the first device die is of a first predetermined area and the ~~second~~ additional device die is of an additional predetermined area, the first predetermined area being greater than the additional predetermined area.

8. (currently amended) The IC of claim 1 ~~wherein,~~ wherein the first device die, having a core region surrounded by a pad ring, includes ground connections in at least one of the following locations: about the center of the first device die in the core region, on predetermined locations about the pad ring of the first device die; and the additional device die, having a core ~~regions~~ region surrounded by a pad ring and ground connections on a predetermined underside ~~location-~~ location includes ground connections in at least one of the following locations: about the center of the additional device die in the core region, on predetermined locations about the pad ring of the additional device die, at predetermined locations on the underside location of the additional device die.

9. (currently amended) The IC of ~~claim 5~~ claim 8 wherein, the ground connections on the predetermined locations of the pad ring of the first device die are coupled to the ground connections on the predetermined locations of the pad ring of the ~~second~~ additional device die are coupled with a plurality of ground straps.

10. (currently amended) The IC of ~~claim 6~~ claim 9 wherein, the plurality of ground straps ~~are comprised of~~ comprise a conductive material including at least one of the following: gold, silver, aluminum, copper, and alloys thereof.

11. (currently amended) The IC of ~~claim 6~~ claim 9, wherein the plurality of ground straps include at least one of the following: a lattice structure, ground straps connecting grounds nearest one another.

12. (currently amended) A method for packaging an integrated circuit having a plurality of die including a first device and ~~at least one~~ an additional device, and having a grounded substrate, the method comprising:

attaching a first device die onto a substrate;
applying an insulating material on the first device die;
attaching an additional device die onto the insulating material; and
~~bonding using a conductive adhesive to bond~~ the first device die to the additional device die at predetermined ground connections on the first device die to predetermined ground connections on the additional device die, and bonding the predetermined ground connections to ground nodes of the substrate.

13. (canceled)

14. (currently amended) The method of claim 12, wherein the insulating material has predefined openings therein, the predefined openings corresponding to the predetermined ground connections on the first device die and the predetermined ground connections on the additional device die.

15. (currently amended) A method for packaging an integrated circuit having a plurality of die including a first device and at least one additional device, the method ~~comprising:~~ comprising:

- attaching a first device die onto a substrate;
- applying ~~an conductive material~~ a conductive adhesive on the first device die; and
- attaching an additional device die onto the ~~conductive material~~ adhesive, wherein the conductive ~~material~~ adhesive connects the first device die at predetermined ground connections to predetermined ground connections on the additional ~~device~~, device die.